

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application:  
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND  
METHOD FOR FABRICATING AND USING THE  
SAME

Confirmation No. 4432

Group Art Unit: 2891

Office: Zarnecke, David A.

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Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT AND REQUEST FOR RECONSIDERATION**

In response to the Office Action mailed on December 8, 2006, please re-consider this application in light of the following amendments and remarks. Applicants have simultaneously filed a petition for a one-month extension of time to extend the period of response to this Office Action until April 8, 2007.

**Amendments to the Claims** being on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.